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(54) Title: TEMPERATURE-CONTROLLED WAFER SUPPORT PEDESTAL WITH VACUUM CLAMPING FEATURES

(57) Abstract: Pedestals, apparatuses, systems and methods for semiconductor processing are provided. An apparatus may have a pedestal body having a first side and a second side facing in an opposite direction from the first side, a plurality of vacuum clamping channels located on the first side, the vacuum clamping channels fluidically connected with a vacuum passage extending through the pedestal body, the plurality of vacuum clamping channels is configured for vacuum clamping a wafer to the first side of the pedestal body, and a first channel positioned on the second side of the pedestal body, the first channel is configured to receive a first temperature control element that is configured to control a temperature of the pedestal body by actively cooling the pedestal body.

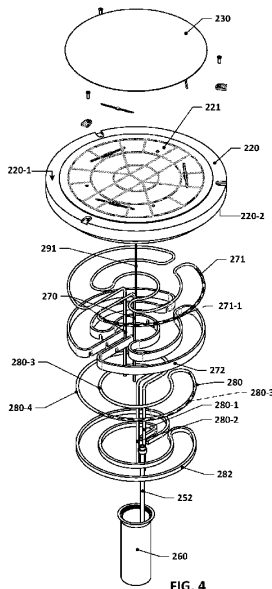


FIG. 4

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